



IEEE DTTIS'2026 Call For Tutorials

Aim of the Tutorials:

IEEE DTTIS 2026 Conference will feature a state-of-the-art set of Tutorial presentations. The Organizing Committee invites proposals and ideas for tutorials to be held as part of the Conference. Tutorials will provide a good opportunity for conference attendees to learn from leaders in the field, explore cutting-edge topics, and acquire new insights, knowledge and skills. The topic should be of sufficient relevance with respect to the general scope of the conference.

Potential organizers are invited to submit a brief (one-page) proposal and addressed to the Tutorial Chair.

Papers are solicited in, but not limited to, the following topics:

Integrated Systems Design

- Analog, digital, mixed, and RF circuits design
- System-on-a-chip (SoC) & System of Chips (SoC), MPSoC, NoC, SIP, and NIP design
- Embedded/ multiprocessor systems
- Hardware design for AI
- AI accelerators
- MEMS, NEMS and MOEMS systems design
- Synthesis (physical, logic,...)
- Simulation, Validation & Verification
- Bio-engineering & Bio-chip design
- Electronics for energy harvesting
- Wireless communication systems design
- Opto-electronic System Design
- Biomedical Circuit & Systems
- Power electronics and systems design
- Sensory Systems Design
- Chiplet and disaggregation
- Intelligent and Autonomous Robotic Systems
- Embedded AI and TinyML
- Real-time inference under power, latency, and memory constraints
- Hardware–software co-design for intelligence at the edge
- Multi-agent coordination and distributed intelligence
- Heterogeneous computing platforms (CPU–GPU–FPGA–ASIC)
- Interoperability across hardware, software, and networks
- Hardware–software co-design for intelligence at the edge

Integrated Systems Testing

- Defect and Fault Modeling
- Analog, digital circuit test
- Mixed, and RF circuit testing
- MEMS/NEMS/MOEMS Testing
- 3D/2.5D Test
- Memory test
- Repair and diagnosis
- Reliability
- DFT, BIST and BISR
- Alternatives test strategies
- Fault Simulation, ATPG
- Yield Optimization
- Automotive reliability and test
- Reliability failures and modeling
- Electronic System Reliability
- Test and Security Issues
- ATE issues
- On-line Testing and fault Tolerance
- Delay testing

Integrated Systems Technology

- Process technologies
- Device modeling
- Material characterization
- Failure analysis
- Emerging technologies
- ICs Packaging
- Process technology
- Reliability issues
- 2.5 & 3D integration
- Circuit integrity



Special Issue

Analog Integrated Circuits and Signal Processing Journal

Tutorial Chair:

- Prof. Hassen Mnif, ENETCOM, Tunisia
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Submission Deadline for Tutorial proposals: June, 30th 2026

Each Tutorial proposal should describe concisely the content, importance and timeliness of the tutorial. It should contain the following sections:

- Tutorial's title.
- Tutorial's type (introductory, intermediate, or advanced)
- Summary describing the main focus and topics to be addressed and explained why the tutorial is appropriate for DTTIS.
- A detailed outline of the presentation.
- A description of the proposer's lecturing expertise.
- The proposed duration of the tutorial

Paper online submission: <https://dttis2026.si2e.tn/>

